



## N-Channel Enhancement-Mode Vertical DMOS FETs

### Ordering Information Standard Commercial Devices

BV <sub>DSS</sub> / BV <sub>DGS</sub>	R <sub>DS(ON)</sub> (max)	I <sub>D(ON)</sub> (min)	Order Number / Package		
			TO-39	TO-92	TO-220
170V	6Ω	1.0A	VN1706B	VN1706L	VN1706D
170V	10Ω	1.0A	—	VN1710L	—

### High Reliability Devices

See pages 5-4 and 5-5 for MILITARY STANDARD Process Flows and Ordering Information.

### Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C<sub>ISS</sub> and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-channel devices

### Applications

- Motor control
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

### Absolute Maximum Ratings

Drain-to-Source Voltage	BV <sub>DSS</sub>
Drain-to-Gate Voltage	BV <sub>DGS</sub>
Gate-to-Source Voltage	± 30V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

\* Distance of 1.6 mm from case for 10 seconds.

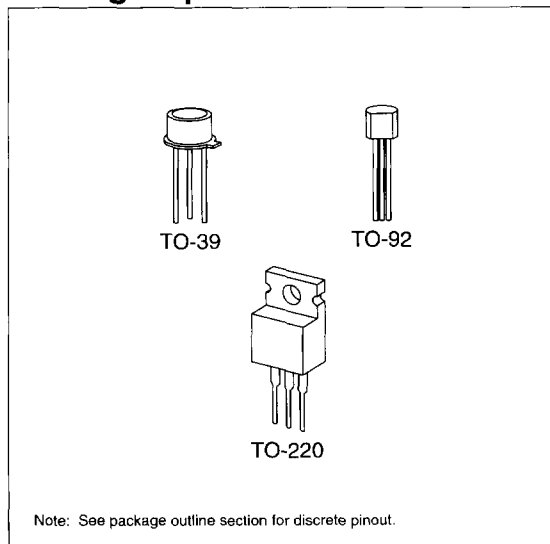
### Advanced DMOS Technology

These enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

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### Package Options



Note: See package outline section for discrete pinout.

## Thermal Characteristics

Package	$I_D$ (continuous)*	$I_D$ (pulsed)	Power Dissipation @ $T_C = 25^\circ\text{C}$	$\theta_{ja}$ $^\circ\text{C/W}$	$\theta_{jc}$ $^\circ\text{C/W}$
TO-39	0.63A	3.0A	6.25W	170	20
TO-92	0.22A	2.3A	0.8W	156	21.3
TO-220	1.12A	3.0A	20W	80	6.25

\*  $I_D$  (continuous) is limited by max rated  $T_j$ .

## Electrical Characteristics (@ $25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Min	Typ	Max	Unit	Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage		170			V	$V_{GS} = 0V, I_D = 100\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage		0.8		2.0	V	$V_{GS} = V_{DS}, I_D = 1\text{mA}$
$I_{GSS}$	Gate Body Leakage				100	nA	$V_{GS} = 15V, V_{DS} = 0V$
$I_{DSS}$	Zero Gate Voltage Drain Current				10	$\mu\text{A}$	$V_{GS} = 0V, V_{DS} = 120V$ $T_A = 125^\circ\text{C}$
					500		
$I_{D(ON)}$	ON-State Drain Current		1.0			A	$V_{GS} = 10V, V_{DS} = 10V$
$R_{DS(ON)}$	Static Drain-to-Source ON-State Resistance	ALL			10	$\Omega$	$V_{GS} = 2.5V, I_D = 0.1\text{A}$
		VN1710			10		$V_{GS} = 10V, I_D = 0.5\text{A}$
		VN1706			6		$V_{GS} = 10V, I_D = 0.5\text{A}$
$G_{FS}$	Forward Transconductance		300			$\text{m}\mathcal{S}$	$V_{DS} = 10V, I_D = 0.5\text{A}$
$C_{ISS}$	Input Capacitance				125	pF	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1\text{MHz}$
$C_{OSS}$	Common Source Output Capacitance				50		
$C_{RSS}$	Reverse Transfer Capacitance				20		
$t_r$	Rise Time				8	ns	$V_{DD} = 60V, I_D = 0.1\text{A}$ $R_{GEN} = 25\Omega$
$t_{d(ON)}$	Turn-ON Delay Time				8		
$t_f$	Fall Time				9		
$t_{d(OFF)}$	Turn-OFF Delay Time				13		
$V_{SD}$	Diode Forward Voltage Drop	VN1710		1.2			
		VN1706		1.2		V	$I_{SD} = 1.4\text{A}, V_{GS} = 0V$

### Notes:

- All D.C. parameters 100% tested at  $25^\circ\text{C}$  unless otherwise stated. (Pulse test:  $300\mu\text{s}$  pulse, 2% duty cycle.)
- All A.C. parameters sample tested.

## Switching Waveforms and Test Circuit

